

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-7 (canceled).

Claim 8 (new): A piezoelectric device comprising:

an element substrate including a piezoelectric element and an electrically conductive pattern connected to the piezoelectric element on a principal surface of the element substrate;

a supporting layer arranged at a periphery of the piezoelectric element on the principal surface of the element substrate;

a cover covering the supporting layer and arranged to provide a groove inside an external periphery of the element substrate, the groove extending entirely around the external periphery of the element substrate;

an insulating reinforcing material arranged to entirely cover portions of the element substrate adjacent to the cover and ranging from the cover to the external periphery of the principal surface of the element substrate; and

an electrically conductive member electrically connected to the electrically conductive pattern so as to pass through the cover and the reinforcing material.

Claim 9 (new): The device according to Claim 8, wherein the cover extends to an outside peripheral surface of the supporting layer as viewed from a direction normal to the principal surface of the element substrate.

Claim 10 (new): The device according to Claim 8, wherein the cover or the supporting layer is made of one of a polyimide resin, a benzocyclobutene resin, and a silicone resin and wherein the reinforcing material is one of an epoxy resin or a silicone resin.

Claim 11 (new): A method for simultaneously manufacturing a plurality of piezoelectric devices comprising the steps of:

providing an element substrate having a piezoelectric element and an electrically conductive pattern connected to the piezoelectric element on a principal surface of the element substrate, and a supporting layer providing around the piezoelectric element; and

a first step of arranging a cover on the supporting layer and then forming a first electrically conductive member penetrating the cover so as to be connected to the electrically conductive pattern;

a second step of removing the cover and/or the supporting layer ranging from the cover to the element substrate at least inside an external periphery of the element substrate so as to form a groove inside the external periphery of the element substrate, the groove extending around the entire external periphery of the element substrate; and

a third step of arranging an insulating reinforcing material on the element substrate and the cover so as to entirely cover portions of the element substrate adjacent to the cover ranging from the cover to the element substrate.

Claim 12 (new): The method according to Claim 11, wherein the step of removing is performed by a laser beam, and the wavelength of the laser beam is about 355 nm or less.

Claim 13 (new): The method according to Claim 11, wherein the groove separates one piezoelectric device from another as viewed from a direction normal to the principal surface of the element substrate.

Claim 14 (new): The method according to Claim 13, further comprising a step, which is performed between the first and second steps, of removing the electrically conductive pattern on the principal surface of the element substrate along the boundary between the piezoelectric devices, each device being a single piezoelectric device.

Claim 15 (new): The method according to Claim 11, wherein the third step includes curing the reinforcing material arranged on the element substrate and the cover in a reduced-pressure atmosphere.

Claim 16 (new): The method according to Claim 11, wherein the third step includes forming a second electrically conductive member penetrating the reinforcing material to be connected to the first electrically conductive member.

Claim 17 (new): The method according to Claim 11, wherein the cover or the supporting layer is made of one of a polyimide resin, a benzocyclobutene resin, and a silicone resin and wherein the reinforcing material is an epoxy resin or a silicone resin.